

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of the claims in the application:

**Listing of Claims:**

Claims 1-12: (canceled)

Claim 13 (previously presented): A method of fabricating a structure comprising:

forming a sacrificial layer over a first surface of a substrate;

forming a silicon layer over the sacrificial layer;

removing the sacrificial layer; and

controlling a residual stress of the silicon layer to insure that the silicon layer has a residual stress within a range of between about -50 to 50 mega-Pascals.

Claim 14 (original): The method of claim 13 further including forming a passageway through the substrate.

Claim 15 (original): The method of claim 13 further including forming a conformal layer over the silicon layer to provide a selected chemical or biological function.

Claim 16 (currently amended): A method of fabricating a structure comprising:

forming a sacrificial layer over a surface of a substrate;

forming a structural layer over the sacrificial layer;

forming a silicon layer over the structural layer;

removing the sacrificial layer; and

~~monitoring a residual stress of the silicon layer controlling the parameters of the silicon layer forming step~~ to insure that the silicon layer has a residual stress within a range of between about -100 to 100 mega-Pascals and a grain structure including grains defining pores therebetween wherein the grains have an approximately hemispherical shape.

Claim 17 (previously presented): A method of fabricating a structure comprising:

forming a sacrificial layer over a first surface of a substrate; and

growing a silicon film over the sacrificial layer at a temperature near the tensile-to-compressive transition temperature of the silicon film, and controlling a residual stress of the silicon film such that the silicon film has a residual stress within a range of about -100 to 100 mega-Pascals and a grain structure including a layer of grains having an approximately hemispherical shape wherein pores are defined by gaps between adjacent grains.

Claim 18 (original): The method of claim 17 wherein the silicon film is formed under a near zero-stress condition.

Claim 19 (original): The method of claim 17 wherein the silicon film has a residual stress within a range of about -50 to 50 mega-Pascals.

Claim 20: (canceled).

Claim 21 (original): The method of claim 17 wherein the silicon film is grown such that a lateral dimension of any pore is less than that of any grain.

Claim 22 (original): The method of claim 17 wherein the silicon film is grown such that a lateral dimension of the pores is between about 10 and 50 nanometers.

Claim 23 (original): The method of claim 17 wherein the silicon film is grown such that the thickness of the film is between about 50 and 150 nanometers.

Claim 24 (original): The method of claim 17 wherein the silicon film is grown such that the roughness of the film is approximately equal to its thickness.

Claim 25 (original): The method of claim 17 further including forming a conformal layer on the silicon film to provide a selected chemical or biological function.

Claim 26: (canceled).

Claim 27 (previously presented): The method of claim 17 wherein the silicon film is used to form a membrane filter structure.

Claim 28 (new): A method of fabricating a structure comprising:  
forming a silicon layer over a first surface of a substrate;  
controlling the parameters of the forming step to insure that the silicon layer has a residual stress within a range of between about -100 to 100 mega-Pascals and a grain structure including a single layer of grains of approximately hemispherical shape defining pores therebetween.